



Material Content Data Sheet



Sales Product Name				ESD206-B1-02ELS E6327		Issued		20. July 2018	
MA#				MA001302518					
Package				PG-TSSLP-2-3		Weight*		0.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.000	0.17		1678		
	noble metal	gold	7440-57-5	0.001	0.65		6500		
	inorganic material	silicon	7440-21-3	0.010	4.82	5.64	48176	56354	
leadframe	non noble metal	nickel	7440-02-0	0.108	51.96	51.96	519639	519639	
wire	non noble metal	copper	7440-50-8	0.001	0.72	0.72	7206	7206	
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1894		
	plastics	epoxy resin	-	0.011	5.50		54998		
	inorganic material	silicondioxide	60676-86-0	0.067	32.24	37.93	322406	379298	
leadfinish	noble metal	gold	7440-57-5	0.004	1.77	1.77	17730	17730	
plating	noble metal	gold	7440-57-5	0.004	1.98	1.98	19773	19773	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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